

SEMI-CONDUCTIVE CERAMIC DISC CAPACITOR (Surface Layer Type)

POE-D09-00-E-09

Ver: 9

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PRODUCT SPECIFICATION

PRODUCT: CERAMIC DISC CAPACITOR

TYPE: CERAMIC DISC CAPACITOR (Surface Layer Type)

CUSTOMER:

DOC. NO.: POE-D09-00-E-09

Ver.: 9

APPROVED BY CUSTOMER

VENDOR:

☐ WALSIN TECHNOLOGY CORPORATION

566-1, KAO SHI ROAD, YANG-MEI

TAO-YUAN, TAIWAN

NO.277,HONG MING ROAD,EASTERN SECTION, GUANG ZHOU ECONOMIC AND TECHNOLOGY

DEVELOPMENT ZONE, CHINA

MAKER: PAN OVERSEAS (GUANGZHOU) ELECTRONIC CO.,LTD.

NO.277,HONG MING ROAD,EASTERN SECTION, GUANG ZHOU ECONOMIC AND TECHNOLOGY DEVELOPMENT ZONE,CHINA







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Record of change

Date Version Description			
2008.6.3	1	1. D16-00-E-09(before) → POE-D09-00-E-01(1 st edition)	
2008.8.22	2	Complete lead code	14-14
		Add last SAP code "H" for halogen and Pb free, epoxy resin.	9
2008.12.12	3	1.Complete the 13 th to 17 th codes of SAP P/N.	4-6
		2.Page layout adjustment.	
2009.8.21	4	1. Change PSA & POE logo to Walsin & POE logo.	
2011/3/8	5	Review the capacitance range, delete the part of 223/333/473/683.	
2013/5/8	6	 Review the Lead diameter φ from 0.60 +/-0.06mm to 0.55+/-0.05mm Review the "shall be omitted when DΦ<6.0 mm & shall be omitted 	6,8
		when D Φ <8.0 mm." to "shall be omitted when D Φ <060 &shall be omitted when D Φ <080 . "	7
		3. Review the Solderability temperature from $255(+5/-0)^{\circ}$ C to 245 ± 5 °C., Solderability time from 2 ± 0.5 s to 5 ± 0.5 s,	10
		PASSIVE SYSTEM ALLIANCE	
2016/3/3	7	1. Review the Available lead code of Lead Configuration.	5
		2. Delete the definition about "Old Part No."	5-6
		3. Review the Specification and test method.	10-12
2017/10/31	8	1. Review the Available lead code of Lead Configuration.	5
2019/7/26	9	1. Review the Hole-down tape width (W0) from 11.0mm min. to 8.0mm min.	7



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1. Part number for SAP system(total eighteen code):

 $\frac{\text{FY}}{\bullet}$ $\frac{500}{\bullet}$ $\frac{104}{\bullet}$ $\frac{\text{Z}}{\bullet}$ $\frac{060}{\bullet}$ $\frac{\text{B}}{\bullet}$ $\frac{20}{\bullet}$ $\frac{\text{C}}{\bullet}$ $\frac{5}{\bullet}$ $\frac{\text{P}}{\bullet}$

• Temperature characteristic:

Code	FY(Y5V)
Operating temperature	-25°C to +85°C
Cap. change	-82%~+22%

2 Rated voltage (Vdc):

Voltage	16V	25V	50V			
Code	160	250	500			

3Capacitance(pF):

Capacitors (pF)	100000	
Code	104	

♦ Capacitance tolerance : Z=+80%-20%

6 Nominal body diameter dimension (Ref. to page. 7 Dφ Code spec.).

6 Code of lead type: Please refer to Item "2.Mechanical".

•Packing mode and lead's length (identified by 2-figure code)

Taping Code	Description
AN	Ammo / Pitch of component:12.7 mm

Bulk Code	Description PASSIVE
3E	Lead's length L: 3.5mm
04	Lead's length L: 4mm
4E	Lead's length L: 4.5mm
20	Lead's length L: 20mm

8Length tolerance

20118111 101011111	770///11 187/1// "			
Code	Description			
A	± 0.5 mm(Only for short kink lead code "D / X / H")	Short lead		
В	±1.0 mm	Short lead		
С	Min.	Long lead		
D	Taping special purpose	Taping		

9Pitch

Code	Description
5	5.0±0.8mm (For Bulk)
5	5.0+0.8mm-0.2mm (For Taping)

Coating code

Code	Description		
P	Halogen free and Pb free, phenolic resin,		
A	raiogen nee and Fo nee, phenone tesm,		



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2. Mechanical:

Available lead code (Phenolic resin coating): (unit: mm)

Lead type	SAP P/N (13-17) digits	Pitch (F)	Lead length (L)	Packing	Lead configuration	
Lead style : B	B20C5	5.0 ± 0.8	20 MIN.	Bulk	D max.	
Straight long lead	BAND5	5.0 +0.8 -0.2	Taping Spec. (Ref.to page.8)	Tap. Ammo	e The F	
	L4EB5	5.0 ± 0.8	4.5 ± 1.0		D max.	
Lead style : L Straight short lead	L05B5	5.0 ± 0.8	5.0 ± 1.0	Bulk		
	L05B0	10 ± 1.0	5.0 ± 1.0		Ø d- - L	
	H3EA5	5.0 ± 0.8	3.5 ± 0.5		D max. T max.	
	H04A5	5.0 ± 0.8	4.0 ± 0.5	S&		
Lead style: H	H4EB5	5.0 ± 0.8	4.5 ± 1.0	Bulk		
Inside kink	H05B5	5.0 ± 0.8	5.0 ±1.0	12/7	× + \	
lead	H20C5	5.0 ± 0.8	20 MIN.	S Su	S T T T T T T T T T T T T T T T T T T T	
	HAND5	5.0 +0.8 -0.2	Taping SPEC. (Ref.to page.8)	Tap. Ammo	0 d→	
	X3EA5	5.0±0.8	3.5 \pm 0.5	ion in the second secon	D max.	
Lead style: X Outside kink lead	X04A5	5.0±0.8	4.0 ± 0.5	Bulk	2.0 max	
	X05B5	5.0±0,8/	5.0 ± 1.0	WIN	S T F Ø d L	

OTOOL COULDING

*** e** (Coating **extension** on leads):

For straight lead style: 1.5mmMax;

For kink lead style: not exceed the kink.

* When Dφ≥11mm, only for bulk, but Dφ≤10mm can do Bulk or Taping.

 $[\]times$ Lead diameter ϕ = 0.55 +/-0.05mm



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3. Capacitance value vs. rated voltage, product diameter:

Manufacturing capacity list							
T.C.	T.C. FY (Y5V) CLASS III						
Rate voltage	16	16V 25V 50V					
Dφ	050	060	050	060	050	060	
D max. (mm)	6.0	7.0	6.0	7.0	6.0	7.0	
T max. (mm)	3.5	3.5	3.5	3.5	3.5	3.5	
100000		104		104		104	

4. Marking:

T. 17141 MILE.					
Marking	(1) (3) (2) (4)				
Temp. char.	Y5V: Shall be omitted				
(1). Rated capacitance	Identified by 3-Figure Code. Ex. 100000pF→"104",				
(2). Capacitance tolerance	Z=+80%-20%				
(2) P. 4. 1. 14	16V&25V Marked with code: 16V→"16V", 25V→"25V"				
(3). Rated voltage	50V Shall be marked "_" under the rated capacitance.				
(4). Manufacturer's identification	50V: Shall be marked as " $\mbox{$\vee$}$ ", but shall be omitted when D Φ <060. 16V&25V: Shall be marked as " $\mbox{$\vee$}$ ", but shall be omitted when D Φ <080.				
·	R 0.				



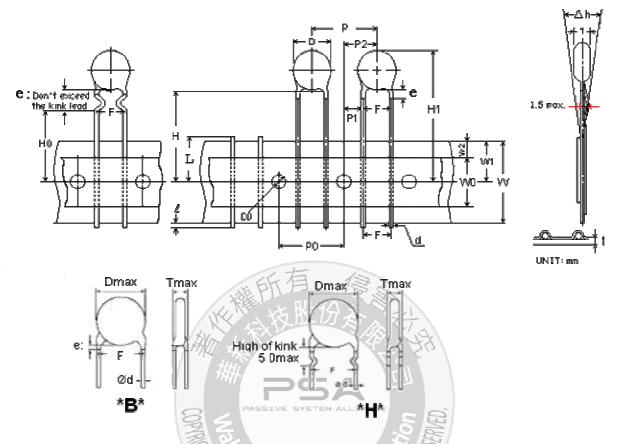
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5. Taping specifications:

* Lead spacing: $F=5.0^{+0.8}_{-0.2}$ (mm)

• 12.7mm pitch/lead spacing 5.0mm taping

Lead code: *BAND5 & *DAND5 & *HAND5



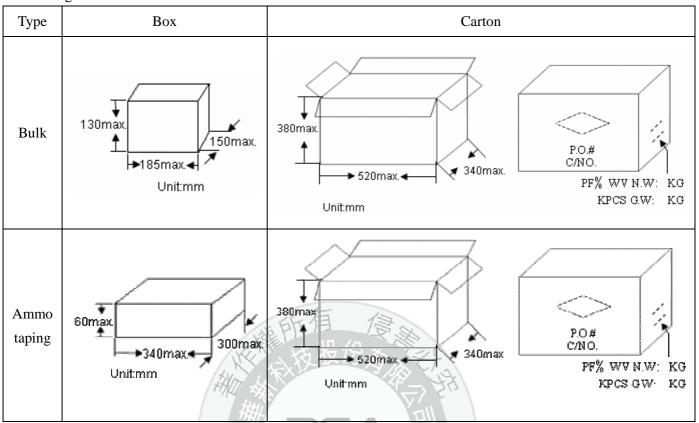
Item (C)			Specification		Remarks	
nem		Symbol	Value	Tolerance	Remarks	
Body diameter	15/1/2	D	06*1	max.	See Section"3. Capacitance value vs. rated	
Body thickness	1/1/	ZALT	*	max.	voltage, product diameter".	
Lead-wire diameter		///_d//-\	0.55	±0.05		
Pitch of component		P	12.7	±1.0		
Feed hole pitch		P0	12.7	±0.3	Cumulative pitch erroe:1.0mm/20 pitch	
Feed hole center to lead		P1	3.85	±0.7	To be measured at bottom of clinch	
Hole center to component center		P2	6.35	±1.3		
Lead-to-lead distance		F	5.0	+0.8,-0.2		
Component alignment, F-R		∆h	0	±2.0		
Tape width		W	18.0	+1.0,-0.5		
Hole-down tape width		W0	8.0	min.		
Hole position		W1	9.0	+0.75,-0.5		
Hole-down tape position		W2	3.0	max.		
Height of component form tape	For straight lead type	Н	20.0	+1.0 -0.5		
center	For kinked lead type	H0	16.0	±0.5		
Component height		H1	32.25	max.		
Lead-wire protrusion		l	2.0	max.	Or the end of lead wire may be inside the tape.	
Food hole diameter		D0	4.0	±0.2		
Total tape thickness		t	0.7	±0.2	Ground paper:0.5±0.1mm	
Length of sniped lead		L	11.0	max.		
Coating rundown on leads		e	Please refer to page 6 "e(Coating extension on leads)".			



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6. Packing Baggage:

6.1 Packing size:



6.2. Pakaging Styles

Bulk: 1000pcs/bag
Taping: 2000pcs/box for Ammo



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7. Specification and test method:

7.1 SCOPE: THIS SPECIFICATION APPLIES TO SEMI-CONDUCTIVE CERAMIC TYPE CAPACITOR.

7.2 TEST CONDITIONS:

UNLESS OTHERWISE SPECIFIED, ALL TESTS SHALL BE OPERATED AT THE STANDARD TEST CONDITIONS OF TEMPERATURE 5° C TO 35° C AND RELATIVE HUMIDITY 45% TO 85%. WHEN FAILS A TEST, RETEST BE OPERATED AT THE CONDITIONS OF TEMPERATURE 25° C $\pm 2^{\circ}$ C, RELATIVE HUMIDITY OF 60% TO 70% AND BAROMETRIC PRESSURE 860 TO 1060 MBAR..

7.3 HANDLE PROCEDURE:

TO AVOID UNEXPECTED TESTING RESULTS FROM OCCURRING, THE TESTED CAPACITOR MUST BE KEPT AT ROOM TEMPERATURE FOR AT LEAST 30 MINUTES AND COMPLETELY DISCHARGED.

7.4 TEST ITEMS:

ITEM	POST-TEST REQUIREMENTS	TESTING PROCEDURE		
APPEARANCE STRUCTURE SIZE	NO ABNORMALITIES	AS STATED IN SECTION 3.		
MARKING		AS STATED IN SECTION 4		
WITHSTAND VOLTAGE	NO ABNORMALITIES	200% RATED VOLTAGE WITH 10mA MAX. CHARGING CURRENT FOR $1\sim5$ SEC.		
INSULATION RESISTANCE	RATED VOLTAGE: $12\sim16\text{VDC}$ LESSER OF $100\text{M}\Omega$ OR $10\text{ M}\Omega \cdot \mu\text{F}$ RATED VOLTAGE: $25\sim50\text{VDC}$ LESSER OF $1000\text{M}\Omega$ OR $20\text{ M}\Omega \cdot \mu\text{F}$	INSULATION RESISTANCE SHALL BE MEASURED AT 60±5 SECONDS , 10±1 VDC		
CAPACITANCE	TOLERANCE: M: ±20% Z: +80-20%	TESTING FREQUENCY : 1 KHZ ± 20 % TESTING VOLTAGE : 0.1 VRMS MAX.		
TEMPERATURE RANGE $95V: -25^{\circ}C \sim +85^{\circ}C$ DISSIPATION $12 \sim 16$ VDC: BELOW 7.5% $25 \sim 50$ VDC: BELOW 5.0%				
		AS ABOVE STIPULATION OF CAPACITANCE		
	CAP. CHANGE : Y5V : WITHIN +22% ∼-82%	CAPACITANCE SHALL BE MEASURED AT 25°C. AND CLASSIFIED AS CAP. CHANGE: -25°C ~85°C Pre-treatment: Capacitor shall be stored at125±3°C for 1hour.then placed at		
TERMINAL STRENGTH	TENSILE STRENGTH : NO BREAKDOWN	WIRE DIA.0.5 M/M, LOADING WEIGHT 0.5KGS FOR 10±1 SECONDS WIRE DIA.0.6 M/M, LOADING WEIGHT 1.0KGS FOR 10±1 SECONDS		
	BENDING STRENGTH : NO BREAKDOWN	WIRE DIA.0.5 M/M, LOADING WEIGHT 0.25 KGS WIRE DIA.0.6 M/M, LOADING WEIGHT 0.5 KGS (BENDING BACK AND FORTH 90 DEGREE TWICE)		
SOLDERBILITY	LEAD WIRE SHALL BE SOLDERED OVER 3/4 OF THE	TO COMPLY WITH JIS-C-5102 8.4 SOLDER TEMPERATURE245±5°C AND DIPPING TIME 5±0.5 SECONDS.		
	CIRCUMFERENTIAL DIRECTION.	FLUX : WEIGHT RATIO OF RESIN 25%.		

^{** 1&}quot;room condition" Temperature:15~35, Relative humidity: 45~75%, Atmospheric pressure:86~106kPa



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ITEM	POST-TEST REQUIREMENTS	TESTING PROCEDURE
SOLDERING HEAT RESISTANCE	APPEARANCE: NO ABNORMALITIES CAP. CHANGE: Y5V: ±30% WITHSTAND VOLTAGE: (BETWEEN TERMINALS) NO ABNORMALITIES	LEAD WIRE OR TERMINALS SHALL BE IMMERSED UP TO 2.0 M/M FORM BODY. (A) BODY DIA. ≤ 5.0mm: INTO THE MOLTEN SOLDER OF WHICH TEMPERATURE: 260(+5/-0)°C FOR 3.0±0.5 SECONDS. (B) BODY DIA. > 5.0mm: INTO THE MOLTEN SOLDER OF WHICH TEMPERATURE 260(+5/-0)°C FOR 5~10 SECONDS. THEN LEAVE AT STANDARD TEST CONDITIONS FOR 1~2 HOURS, THEN MEASURED. * WHEN SOLDERING CAPACITOR WITH A SOLDERING IRON, IT SHOULD BE PERFORMED IN FOLLOWING CONDITIONS. TEMPERATURE OF IRON-TIP: 350~400 °C SOLDERING IRON WATTAGE: 50W MAX.
HUMIDITY CHARACTERISTIC (STABLE SITUATION)	APPEARANCE: NO ABNORMALITIES CAP. CHANGE: Y5V: $\pm 30\%$ D.F.: $12 \sim 16 \text{VDC}$; $10 \% \text{ MAX}$. $25 \sim 50 \text{VDC}$: $7.5\% \text{ MAX}$. INSULATION RESISTANCE: $12 \sim 16 \text{VDC}$: LESSER OF $50 \text{ M}\Omega$ OR $5 \text{ M}\Omega \cdot \mu\text{F}$ $25 \sim 50 \text{VDC}$: LESSER OF $500 \text{M}\Omega$ OR $20 \text{ M}\Omega \cdot \text{MF}$	SOLDERING TIME : 3.5 SEC. MAX. CAPACITORS SHALL BE SUBJECTED TO A RELATIVE HUMIDITY OF $90 \sim 95\%$ AT $40\pm2\%$ FOR $500(\pm24/-0)$ HOURS. THEN DRIED FOR24±2 HOURS AND MEASURED.
HUMIDITY LOADING	APPEARANCE : NO ABNORMALITIES CAP. CHANGE : Y5V : $\pm 30\%$ D.F. : $12 \sim 16$ VDC : 10% MAX. $25 \sim 50$ VDC : 7.5% MAX. INSULATION RESISTANCE : $12 \sim 16$ VDC : LESSER OF 50 M Ω OR 5 M Ω · μ F $25 \sim 50$ VDC : LESSER OF 500M Ω OR 20 M Ω · μ F	CAPACITORS SHALL BE SUBJECTED TO A RELATIVE HUMIDITY OF 90 ~ 95 % AT 40 ± 2°C FOR 500(+24/-0) HOURS WITH RATED VOLTAGE APPLIED WITH 10MA MAX. THEN DRIED FOR 24±2 HOURS AND MEASURED. Pre-treatment: Capacitor shall be stored at125±3°C for 1hour.then placed at 1room condition for 24±2hours

[※]1"room condition" Temperature:15~35, Relative humidity: 45~75%, Atmospheric pressure:86~106kPa



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ITEM	POST-TEST REQUIREMENTS	TESTING PROCEDURE
	APPEARANCE :	CAPACITORS SHALL BE SUBJECTED TO A TEST OF
	NO ABNORMALITIES	150% RATED VOLTAGE WITH 10MA MAX. FOR HIGH
	CAP. CHANGE :	$1000(+48/-0)$ HOURS AT $85\pm2^{\circ}$ C AND THEN DRIED FOR
	Y5V: ± 30%	24±2 HOURS AND MEASURED
HIGH	D.F.: 12~16VDC: 10 % MAX.	
TEMPERATURE	25~50VDC: 7.5% MAX.	Pre-treatment:
LOADING	INSULATION RESISTANCE :	Capacitor shall be stored at125±3℃ for 1hour.then placed at
	$12\sim$ 16VDC: LESSER OF 50 MΩ	
	OR 5 MΩ · μF	13
	25~50VDC: LESSER OF 500MΩ	(A) X (B) X
	OR 20 MΩ · μF	月余艺
	APPEARANCE:	CAPACITORS SHALL BE SUBJECTED
	NO ABNORMALITIES	CTO:
	CAP. CHANGE:	$-25\pm3^{\circ}$ C (30±3min) $\rightarrow 25^{\circ}$ C (3min) $\rightarrow 85\pm3^{\circ}$ C (30±3min)
	Y5V: ±30% MAX	\rightarrow 25°C (3min) FOR 5 CYCLE.
	D.F.	Pre-treatment:
	≤16VDC: 10% MAX	Capacitor shall be stored at 125±3°C for 1 hour, then placed
TEMPERATURE	25VDC~50VDC: 7.5%MAX	at%1room condition for 24±2hours
CYCLING	INSULATION RESISTANCE :	
	INSULATION RESISTANCE:	
	\leq 16VDC: LESSER OF 50 M Ω	
	OR 5 MΩ*uF	
	25VDC~50VDC:	
	LESSER OF 50 M Ω	
	OR 5 MΩ*uF	

^{* 1&}quot;room condition" Temperature: 15~35, Relative humidity: 45~75%, Atmospheric pressure: 86~106kPa



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8. Cautions & notices:

※Application: DC or Low frequency High Voltage circuits.

As coupling and decoupling capacitors for such application where higher losses and a reduced capacitance stability are required.

8.1. Caution (Rating)

I. Operating Voltage

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the Vp-p value of the applied voltage or the Vo-p which contains DC bias within the rated voltage range.

When the voltage is applied to the circuit, starting or stopping may generate irregular voltage for a transit period because of resonance or switching. Be sure to use a capacitor with a rated voltage range that includes these irregular voltages.

Voltage	DC Voltage	DC+AC Voltage	AC Voltage
Positional measurement	V0-p	V0-p	Vp-p

II. Operating Temperature and Self-generated Heat

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself. When the capacitor is used in a high frequency current, pulse current or similar current, it may self-generate heat due to dielectric loss. The frequency of the applied sine wave voltage should be less than 10kHz. The applied voltage load (*) should be such that the capacitor's self-generated heat is within 20°C at an atmosphere temperature of 25°C. When measuring, use a thermocouple of small thermal capacity-K of Ø0.1mm in conditions where the capacitor is not affected by radiant heat from other components or surrounding ambient fluctuations.

Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. (Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.)

III. Fail-Safe

When capacitor is broken, failure may result in a short circuit. Be sure to provide an appropriate fail-safe function like a fuse on your product if failure would follow an electric shock, fire or fume.

8.2. Caution (Storage and operating condition)

I. Operating and storage environment

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed –10 to 40 degrees centigrade and 15 to 85 % for 6 months maximum and use within the period after receiving the capacitors.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.



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8.3. Caution (Soldering and Mounting)

I. Vibration and impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

II. Soldering

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element. When soldering capacitor with a soldering iron, it should be performed in following conditions.

Temperature of iron-tip: 400 degrees C. max.

Soldering iron wattage: 50W max.

Soldering time: 3.5 sec. max.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.

8.4. Caution (Handling)

Vibration and impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PROUCT IS USED.

8.5. Notice

PASSIVE SYSTEM ALLIANCE

8.5.1. Notice (Soldering and Mounting)

Cleaning (ultrasonic cleaning)

To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity: Output of 20 watts per liter or less.

Rinsing time: 5 min. maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

8.5.2. Notice (Rating)

Capacitance change of capacitor

Class 3 series:

Capacitors have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor is left on for a long time. Moreover, capacitance might change greatly depending on the surrounding temperature or an applied voltage. So, it is not likely to be suitable for use in a time constant circuit.

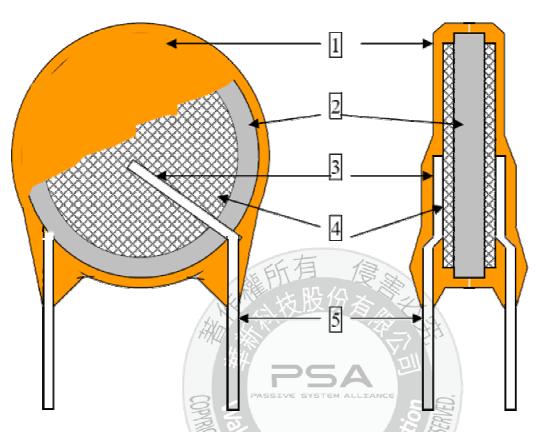
Please contact us if you need detailed information.



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9. Drawing of internal structure and material list:

產品結構圖



NO.	部位	材質	構成部份	供應商
	Part name	Material Con-	Component	Vendor
1	Insulation Coating	Phenolinsulating varnish	Phenolpolymer, Filler, Pigment	Namics
2	Dielectric Element	Ceramic	BaTiO3	Hua Xing Wang Feng
				Fenghua
3	Solder	Solder Tin-silver	Sn97.5-Ag2.5	Huajun
	Solder	THI SHIVE	51177.5 11g2.5	Haili
4	Electrodes	Λα	Silver,Glass frit	Daejoo
4	Electiones	Ag	Silver, Glass IIIt	Xinguang
		Tinned copper	Substrate metal:Fe&Cu	Hengtai
5	Leads wire	clad steel wire		Wuhu
		ciad steel wife	Surface plating:Sn 100%	Taililai